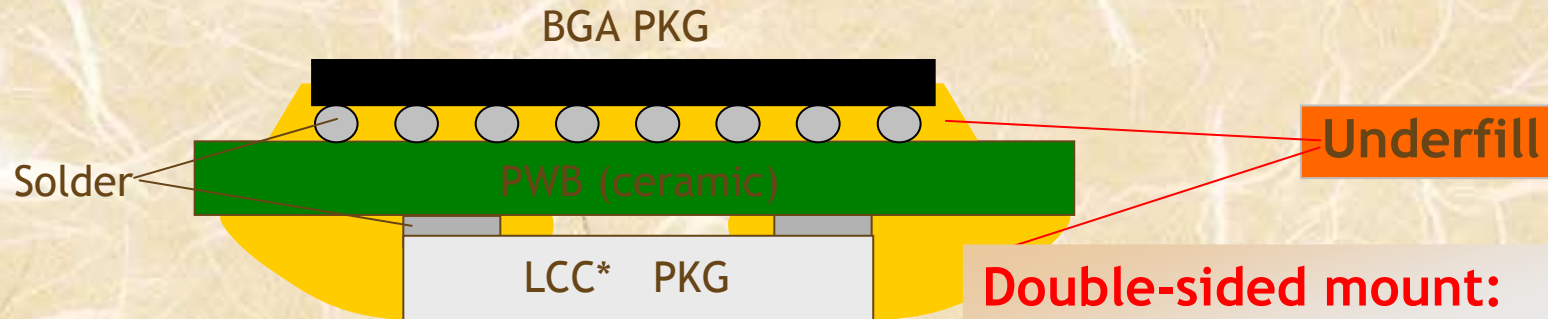


Underfill

Low-temperature thermosetting / Double sided mount



*:Leadless Chip Carrier

Double-sided mount

Double-sided mount:

Robustness in higher stress

Low temperature thermosetting:

80degC

Higher bonding strength

Use epoxy resin / coupling agent that is highly reactable with the material of the devices

Lower CTE

More inorganic filler content in the resin

Low-temperature thermosetting feature

Use hardening accelerator which react at the lower temperature.

Optimize the composition.

Reliability exceeding 10 years

- TCT: -40degC - 85 degC, 3000cyc
- HT: 125degC, 1500h
- LT: -40degC, 1500h
- HHB: 85degC, 85RH%, 1500h